

## ABSTRACT

Incorporating organophilic clay into hot melt adhesive compositions, particularly those comprising semi-crystalline, thermoplastic polymers, greatly  
5 improves the adhesive properties in many respects. Some of these improvements are particularly beneficial to the specific use of hot melt adhesives filled with electrically conductive particles for use as electrically conductive adhesives.

DBK848

10

09896655 062904  
T05290" 55996660